

TRANSMITTAL

Electronic Version v1.1

Stylesheet Version v1.1.0

Title of Invention	Solder Film Manufacturing Method, Heat Sink Furnished with Solder Film, and Semiconductor-Device-and-Heat-Sink Junction
Application Number :	
Date :	
First Named Applicant:	Mr. Katsuhiro Itakura
Confirmation Number:	
Attorney Docket Number:	39.036

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Submitted By:	Elec. Sign.	Sign. Capacity
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Documents being submitted:	Files
us-assignment	SM036-usassn.xml us-assignment.xsl us-assignment.dtd assgn.tif
us-request	SM036-usrequ.xml us-request.dtd us-request.xsl
us-fee-sheet	SM036-usfees.xml us-fee-sheet.xsl us-fee-sheet.dtd
application-body	SM036-trans.xml us-application-body.xsl application-body.dtd wipo.ent mathml2.dtd mathml2-qname-1.mod isoamsa.ent isoamsb.ent isoamsc.ent isoamsn.ent isoamso.ent isoamsr.ent isogrk3.ent isomfrk.ent isomopf.ent isomscr.ent isotech.ent isobox.ent isocyr1.ent isocyr2.ent isodia.ent isolat1.ent isolat2.ent isonum.ent isopub.ent mmlextra.ent mmlalias.ent soextblk.dtd dclr01.tif dclr02.tif dclr03.tif
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